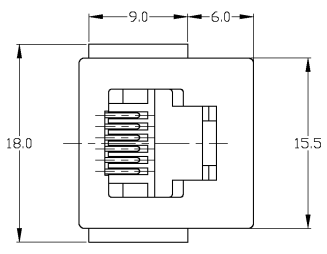


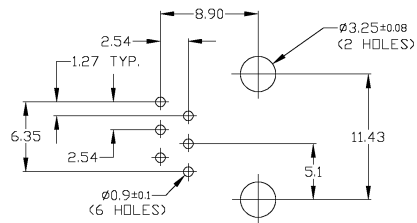
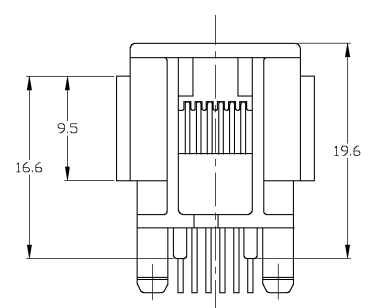
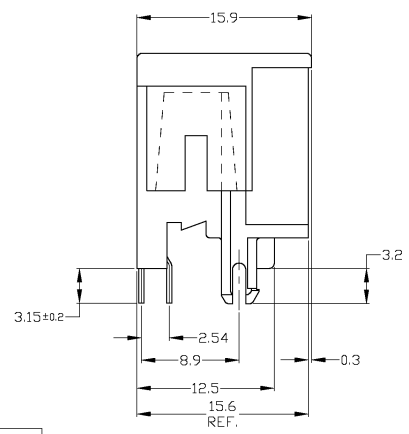
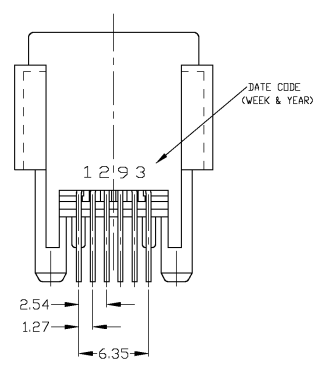
DO NOT SCALE
DIMENSIONS IN mm

METRIC

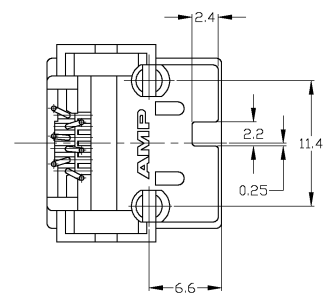


NOTES:

- 1 TOLERANCES UNLESS OTHERWISE SPECIFIED: $\pm 0,15$
- 2 FOR APPLICATION INFORMATION SEE AMP SPEC. 114-19019
- 3 FOR PERFORMANCE REQUIREMENTS SEE AMP SPEC. 108-19064
- 4 PACKAGING: BULK PACKAGED.
TRUE POSITIONING OF THE SOLDER TINES
MAY BE AFFECTED BY BULK PACKAGING.



PRINTED CIRCUIT BOARD LAYOUT
[VIEW SHOWN IS CIRCUIT (NONCOMPONENT) SIDE OF BOARD.]
PRINTED CIRCUIT BOARD THICKNESS: 1,6 mm NOMINAL.
TOLERANCES UNLESS OTHERWISE SPECIFIED $\pm 0,05$.



6 POSITIONS / 6 CONTACTS	IN CONTACT AREA 1,2µm MIN SEL HARD GOLD OVER 1,2µm MIN NICKEL	HOUSING PBT, UL 94V-0 COLOR: BLACK	100190-2
REMARKS	FINISH	MATERIAL	P/N
F SR10-0084-02	KV	06 FEB 02	CUSTOMER DRAWING
E DI-1142-97	EdE	19 NOV 97	FOR REFERENCE ONLY WILL NOT BE UPDATED
D DI-0217-93	R.D.	04-11-03	THIS DRAWING IS UNPUBLISHED
C H-9194	D.K.	09-03-92	RELEASED FOR PUBLICATION
B H-9194	JvdH	16-10-91	NAME: MODULAR JACK, 6 POS., TOP ENTRY
A H-9194	JvdH	09-10-91	FOR PROFILE, WITH PANEL STOPS
LTR	REVISION RECORD	DR. CHK. DATE	FOR PRINTED CIRCUIT BOARD
DR.: J.V.D.HEDSEN	CHK.: C.STERNEN	APP.: L.V.SEST	DWG. No. C-100190
DATE: 08-10-91	DATE:	DATE:	REV. LTR. F 1 of 1
4	3	2	A2

11 10 9 8 7 6 5 4 3 2 1